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(54) Title: A PROCESS FOR THE PRODUCTION OF A NITROGENOUS LAYER ON A SEMICONDUCTOR OR METAL
SURFACE

(57) Abstract: A first process for the production of a thin nitrogenous layer on a semiconductor surface by contacting at least a part of the surface with a nitrogenous liquid, by applying an electrical voltage between the surface, the liquid and an electrode according to a given voltage-time curve until a layer thickness of less than 5 nm is formed, and then separating the surface from the liquid. A second process for the production of a thin nitrogenous layer on a metal surface or on a metal layer located on a substrate by contacting at least a part of the surface or the metal layer with a nitrogenous liquid, by applying an electrical voltage between the surface or metal layer, the liquid and an electrode according to a given voltage-time curve until a layer thickness of less than 50 nm is formed, and then separating the surface or the metal layer from the liquid. A third process for detaching an oxygen-containing and/or nitrogenous layer on a semiconductor or a metal surface.

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